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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/568,514	· 10/26/2006	Kathirgamasundaram Sooriakumar	207,468	1169
7590 06/12/2007 ABELMAN, FRAYNE & SCHWAB			EXAMINER	
10th Floor			PATEL, REEMA	
666 Third Ave. New York, NY 10017		ART UNIT	PAPER NUMBER	
			2812	
		·	MAIL DATE	DELIVERY MODE
			06/12/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

	Application No.	Applicant(s)				
	10/568,514	SOORIAKUMAR ET AL.				
Office Action Summary	Examiner	Art Unit				
	Reema Patel	2812				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the	correspondence address				
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period w  - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATIO 36(a). In no event, however, may a reply be till apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. mely filed the mailing date of this communication. ED (35 U.S.C. § 133).				
Status	*					
1) Responsive to communication(s) filed on 15 Fe	ebruary 2006.					
2a) This action is <b>FINAL</b> . 2b) ⊠ This						
3) Since this application is in condition for allowar	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the practice under E	x parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.				
Disposition of Claims						
4) ⊠ Claim(s) 1-20 is/are pending in the application. 4a) Of the above claim(s) is/are withdraw 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-5 and 16 is/are rejected. 7) ⊠ Claim(s) 6-15 and 17-20 is/are objected to. 8) □ Claim(s) are subject to restriction and/or	vn from consideration.					
Application Papers  9)☐ The specification is objected to by the Examine	_					
10)⊠ The drawing(s) filed on <u>16 February 2006</u> is/are Applicant may not request that any objection to the o Replacement drawing sheet(s) including the correcti	e: a)⊠ accepted or b)⊡ objected drawing(s) be held in abeyance. Se ion is required if the drawing(s) is ob	e 37 CFR 1.85(a). ojected to. See 37 CFR 1.121(d).				
11) The oath or declaration is objected to by the Ex	aminer. Note the attached Office	e Action or form PTO-152.				
Priority under 35 U.S.C. § 119		·				
<ul> <li>12) Acknowledgment is made of a claim for foreign</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents</li> <li>2. Certified copies of the priority documents</li> <li>3. Copies of the certified copies of the prior application from the International Bureau</li> <li>* See the attached detailed Office action for a list of</li> </ul>	s have been received. s have been received in Applicat rity documents have been receiv ı (PCT Rule 17.2(a)).	ion No ed in this National Stage				
Attachment(s)						
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date 11/17/06.	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:	ate				

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#### **DETAILED ACTION**

### **Priority**

1. Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

### Information Disclosure Statement

2. The information disclosure statement (IDS) was submitted on 11/17/06. The submission is in compliance with the provisions of 37 CFR 1.97. Accordingly, the information disclosure statement has been considered by the examiner.

## Claim Objections

3. Claims 6-15 and 17-20 are objected to under 37 CFR 1.75(c) as being in improper form because a multiple dependent claim should refer to other claims in the alternative only and cannot depend from any other multiple dependent claim. See MPEP § 608.01(n). Accordingly, the claims have not been further treated on the merits.

# Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 1-3, 5 and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Chong et al. (WO 03/065050 A2) in view of McNeil et al. (U.S. 6,845,670 B1).
- 6. Regarding claim 1, Chong et al. discloses the following claimed elements:
  - A method of fabricating an accelerometer including the steps of:

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- Providing a first wafer of insulating material having a first major surface and a second major surface (page 8, lines 3-6);
- Etching at least two cavities in the first major surface of the first wafer (page 8, lines 23-25; Fig. 3);
- Providing a second wafer of semi-conducting material (page 8, lines 27-28);
- Bonding the first major surface of the first wafer to the first major surface of the second wafer (page 8, lines 27-30);
- Depositing and patterning metallization on the second major surface of the second wafer (page 9, lines 14-16);
- Depositing and patterning a masking layer on the second major surface of the second wafer (page 9, lines 18-26);
- Etching the second major surface of the second wafer to form the accelerometer (page 9, line 28 – page 10, line 2);
- Removing the masking layer from the second major surface of the second wafer (page 10, lines 4-7).
- 7. Yet, Chong et al. does not disclose forming an accelerometer which has a third sensor to detect acceleration in a third (out-of-plane) axis and hence does not disclose patterning metal onto the first major surface of the first wafer to form electrical connections for a third accelerometer. However, McNeil et al. discloses patterning metal onto a wafer to form electrodes so as to produce an accelerometer to sense acceleration in the out-of-plane or z-axis (col 1, lines 37-57). Therefore, it would have

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been obvious to one having ordinary skill in the art at the time the invention was made to modify the invention of Chong et al. with patterning metal on a first wafer so as to provide an additional acceleration sensor to sense acceleration in the z-axis.

- 8. Regarding claim 2, Chong et al. discloses the first wafer is an insulating material (page 3, lines 8-9).
- 9. Regarding claim 3, Chong et al. discloses the first wafer is formed of glass (page 3, lines 8-9).
- 10. Regarding claim 5, Chong et al. discloses the etch step used to form cavities in the first major surface of the first wafer is an anisotropic etch (page 8, lines 23-24).
- 11. Regarding claim 16, Chong et al. discloses the beams are anchored to the wafer (page 3, line 11).
- 12. Claims 4 is rejected under 35 U.S.C. 103(a) as being unpatentable over Chong et al. (WO 03/065050 A2) in view of McNeil et al. (U.S. 6,845,670 B1) as applied to claim 1 above, and further in view of Lee (U.S. 4,934,190).
- 13. Regarding claim 4, Chong et al. and McNeil et al. discloses the first wafer is formed of glass (Chong et al., page 3, lines 8-9) but do not specify that it be made of borosilicate glass. However, Lee discloses the use of a substrate comprising borosilicate glass in the manufacture of a sensor device (col 5, lines 60-63). Such a material is preferential since it is a relatively less expensive material and has a low thermal coefficient of expansion, which minimizes warping due to high temperature bonding. Therefore, it would have been obvious to one having ordinary skill in the art at

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the time the invention was made to modify the invention of Chong et al. and McNeil et al. with a first wafer of borosilicate glass, as taught by Lee so as to use a less expensive substrate material and minimize possible warping.

14. Regarding claim 5, Chong et al. discloses the etch step used to form cavities in the first major surface of the first wafer is an anisotropic etch (page 8, lines 23-24).

### **Conclusion**

15. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Kumagai et al. (U.S. 2003/0217597 A1) discloses a method of manufacturing an accelerometer.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Reema Patel whose telephone number is 571-270-1436. The examiner can normally be reached on M-F, 8:00-4:30 EST.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Michael Lebentritt can be reached on 571-272-1873. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

RSP 6/6/07 SCOTT B. GEYER
PRIMARY EXAMINER

6/6/07

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